

LINEAR IC

6-CHANNEL 8-BIT A/D CONVERTER

MB4053

6-CHANNEL 8-BIT A/D CONVERTER SUBSYSTEM

The Fujitsu MB4053 is 6-channel, 8-bit, single-slope A/D converter subsystem designed to be used in a microprocessor based data control system. This device provides the analog functions while the addressing, counting and timing functions are provided by a microprocessor such as the MB8840/50, MBL8048, or MBL6801.

The MB4053 is single monolithic bipolar IC providing a 1 of 8 address decoder, 8-channel analog multiplier, sample and hold, constant current generator, ramp integrator and comparator in a 16-pin package.

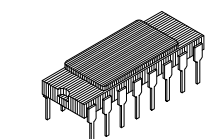
This A/D converter subsystems are suitable for a wide range of applications. The resolution required by an application can be obtained by arbitrarily selecting a suitable integration time. Also zero offset and full-scale error corrections can be made automatically (auto-zero and auto-calibration) to minimize conversion error.

- Microprocessor compatible
- Digital input/output: : TTL compatible
- Zero offset and full-scale error correction capability
- Ratiometric conversion capability
- Available in 16-pin DIP and Flat Pack
- Compatible with MC 14443 and μ A9708 (DIP package)
- Single power supply : +4.75 V to +15V
- Excellent linearity : $\pm 0.2\%$ max. error
- Fast conversion time : 300 μ s/ch typ.
- Analog input voltage : 0V to V_{CC} -2V (5.25V max.)
- Power Dissipation : 25mW typ. at V_{CC} = 5V

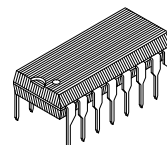
ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Supply Voltage	V_{CC}	18	V
Digital Input Voltage	V_{IND}	-0.5 to +30	V
Digital Output Voltage when Off	V_{OH}	-0.5 to +18	V
Analog Input Voltage	V_{INA}	-0.5 to +30	V
Output Current	I_O	10	mA
Storage Temperature	Ceramic	T_{STG}	-55 to +150
	Plastic		-55 to +125

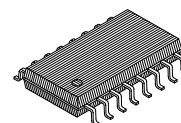
NOTE: Permanent device damage may occur if the above **Absolute Maximum Ratings** are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



**CERAMIC PACKAGE
DIP-16C-F02**

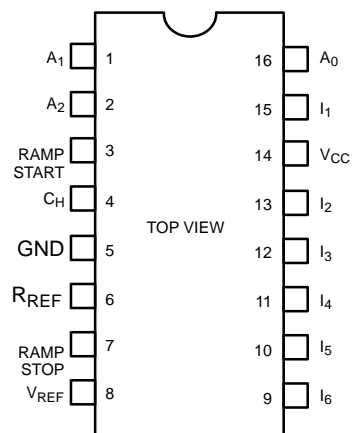


**PLASTIC PACKAGE
DIP-16P-M04**



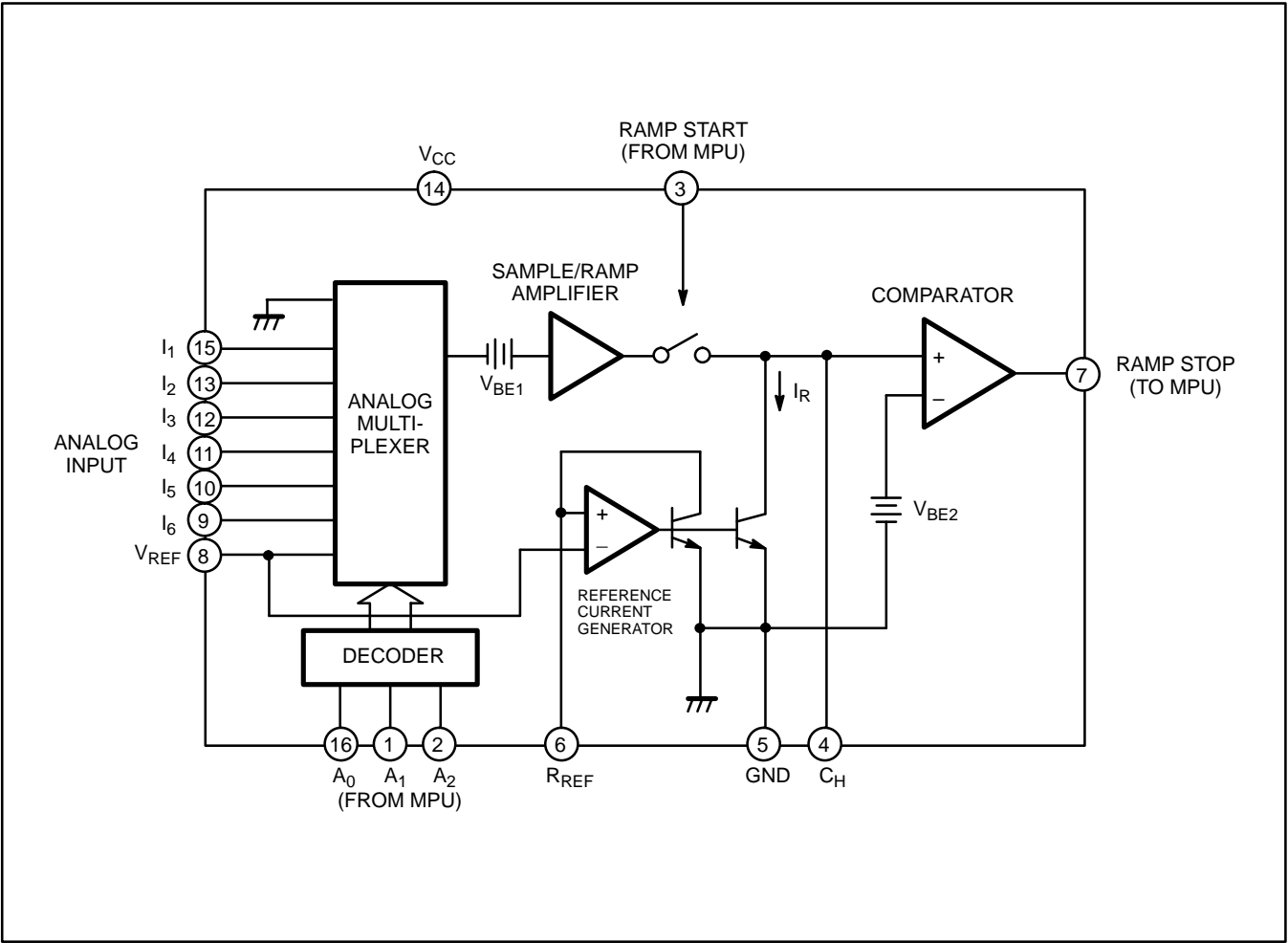
**PLASTIC PACKAGE
FPT-16P-M06**

PIN ASSIGNMENT



This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields. However, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high impedance circuit.

BLOCK DIAGRAM



RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Value			Unit
		Min	Typ	Max	
Supply Voltage	V_{CC}	4.75	5.0	15	V
Reference Voltage*	V_{REF}	2.0	—	5.25	V
Ramp Capacity	C_H	300	—	—	pF
Reference Current	I_R	12	—	50	μA
Analog Input Voltage	V_{IA}	0	—	V_{REF}	V
Output Current	I_O	—	—	1.6	mA
Operating Temperature	T_a	−40	—	+85	°C

* : $2V \leq V_{REF} \leq V_{CC} - 2V$

ELECTRICAL CHARACTERISTICS

($V_{CC} = 4.75V$ to $15V$, $T_a = -40^\circ C$ to $85^\circ C$)

Parameter	Symbol	Values			Unit	Remarks
		Min	Typ	Max		
Conversion Error	E_A	—	± 0.2	± 0.3	%	*1
Linearity Error	E_R	—	± 0.08	± 0.2	%	*2
Analog Input Current	I_B	—	−50	−250	nA	
Crosstalk Between Any Two Channels	V_{CR}	60	—	—	dB	*3
Multiplexer Input Offset Voltage	V_{OSM}	—	2.0	4.0	mV	
Conversion Time	t_C	—	296	350	$\mu s/ch$	See test circuit Analog input: 0 thru V_{REF} $C_H = 3300$ pF, $I_R = 50\mu A$
Acquisition Time	t_A	—	20	40	μs	See test circuit $C_H = 1000$ pF *4
Acquisition Current	I_A	150	—	—	μA	
Ramp Start Delay Time	t_O	—	100	—	ns	
Multiplexer Address Time	t_M	—	1	—	μs	
Digital High Level Input Voltage	V_{IH}	2.0	—	—	V	
Digital Low Level Input Voltage	V_{IL}	—	—	0.8	V	
Digital Low Level Input Current	I_{IL}	—	−5	−15	μA	$V_{IL} = 0.4V$
Digital High Level Input Current	I_{IH}	—	—	1	μA	$V_{IH} = 5.5V$
High Level Output Current	I_{OH}	—	—	10	μA	$V_{OH} = 15V$
Low Level Output Voltage	V_{OL}	—	—	0.4	V	$I_{OL} = 1.6mA$
Supply Current	I_{CC}	—	5	10	mA	

A minus sign (−) prefixing a current value indicates that the current flows from the IC to the external circuit.

*1: Conversion error: For all channels, deviation from a straight line between two points obtained by channel addresses 000 (0 scale) and 111 (full scale).

*2: Linearity error; Deviation from a straight line between the 0 and full scale points for each channel.

*3: Crosstalk between channels: Voltage change V_{CH} of C_H terminal occurring when an input voltage of a channel is changed by ΔV_1 while another channel is already charged (RAMP START = 0). This calculated by $20 \log \frac{\Delta V_{CH}}{\Delta V_1}$.

*4: Acquisition time: Sum of multiplexer delay time, RAMP START delay time, and time required to charge the selected input voltage to the ramp capacitor.

Fig. 1 – CONVERSION ERROR

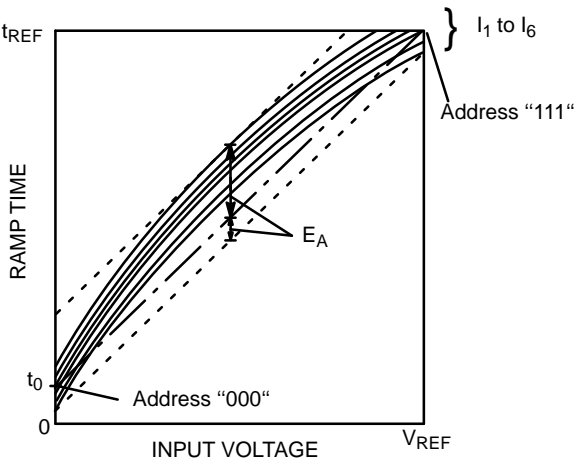


Fig. 2 – LINEARITY ERROR

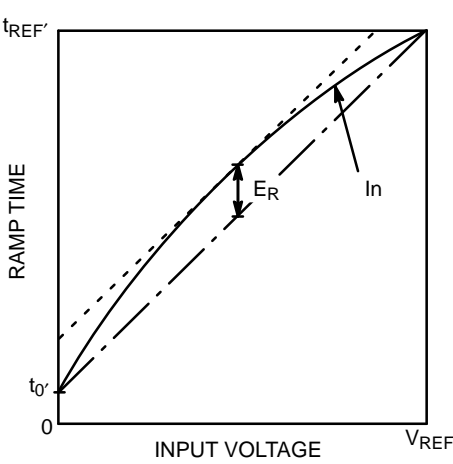
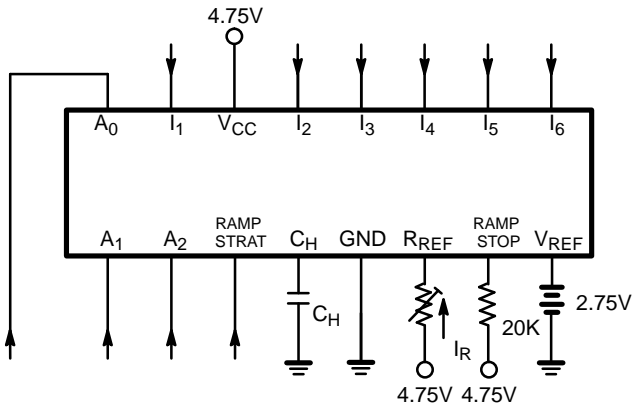


Fig. 3 – ACQUISITION/CONVERSION TIME TEST CIRCUIT

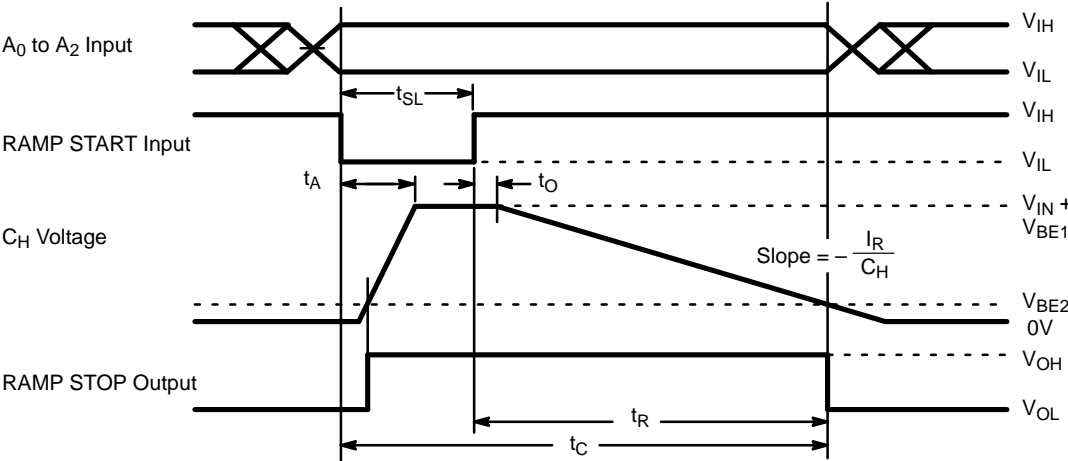


NOTE: Adjust R_{REF} in the range 40 to 200K Ω so that I_R is 12 to 50 μ A.

CHANNEL SELECTION

Input address line			Selected analog input
A_2	A_1	A_0	
0	0	0	GND
0	0	1	I_1
0	1	0	I_2
0	1	1	I_3
1	0	0	I_4
1	0	1	I_5
1	1	0	I_6
1	1	1	V_{REF}

Fig. 4 – TIMING CHART



OPERATION DESCRIPTION

Refer to BLOCK DIAGRAM, and Fig.4 Timing Chart. Address inputs A_0 to A_2 are used to select the analog input to be converted, (one of the six analog inputs I_1 to I_6). The RAMP START input is switched from a logic 1 to a logic zero. This causes the external ramp capacitor C_H to charge at a fixed rate. (Note 1) until it reaches the sum of the selected analog input voltage and a constant offset voltage V_{BE1} . The RAMP STOP output (open-collector) switches from a logic 0 to logic 1 when the voltage on C_H reaches the comparator reference voltage V_{BE2} . The RAMP START input is switched back to a logic 1 after C_H is completely charged. This disconnects the analog input from C_H and allows it to be discharged at a fixed rate (Note 2). When the voltage on C_H reaches the comparator reference voltage V_{BE2} the RAMP STOP output switches back to a logic 0. This completes a conversion cycle for 1 channel.

The time between the RAMP START input switching ($0 \rightarrow 1$) and RAMP STOP output switching ($1 \rightarrow 0$) is the RAMP TIME t_R . This would be directly proportional to the analog input voltage for the ideal situation where there was no comparator switching level error, leakage, switching delay times or effect of the impedance of the internal reference current source. t_R can be calculated for the ideal case as follows:

$$t_R = V_{IN} \times \frac{C_H}{I_R}$$

Where: V_{IN} = Analog input voltage to be measured

C_H = External ramp capacitor

$$I_R = \frac{V_{CC} - V_{REF}}{R_{REF}}$$

This ramp time is converted to a digital representation by counting t_R with the microprocessor. If a small error can be tolerated, the A/D conversion software can be reduced and the conversion time minimized by omitting corrections.

NOTE:

$$*1 \text{ Charge slope} = \frac{I_A - I_R}{C_H} \geq \frac{150\mu A - I_R}{C_H}$$

Where: I_A is the acquisition current whose value is determined from the circuit constant in the IC.

$$*2 \text{ Discharge slope} = - \frac{I_R}{C_H}$$

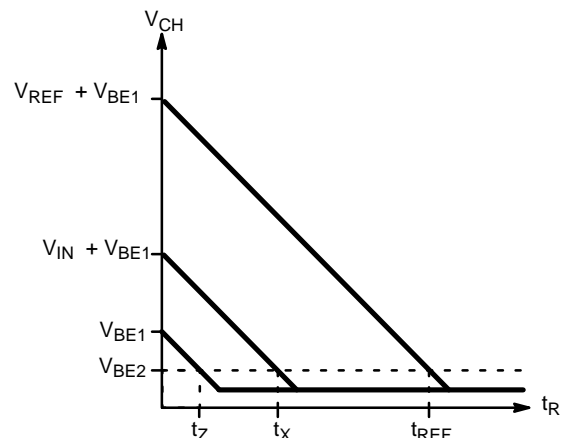
ZERO OFFSET AND FULL-SCALE FACTOR CORRECTIONS

High precision conversions can be achieved by correcting for zero offset and full scale factor as follows:

The channel select address (A_0 to A_2) is set to 000. Ground (GND) is selected (internally) as the analog input and converted. This results in ramp time t_R . Next the address is set to 111. V_{REF} is selected (internally) and converted. This results in ramp time, t_{REF} . Finally the desired analog input (one of I_1 to I_6) is selected and converted. This results in ramp time t_X . This conversion sequence is arbitrary and the GND and V_{REF} conversions are not needed each time a channel is converted but only as required for calibration. The relationships between the inputs and ramp times are shown below.

$$\begin{aligned} (V_{BE1})_C &= t_Z \\ (V_{REF} + V_{BE1})_C &= t_{REF} \\ (V_{IN} + V_{BE1})_C &= t_X \\ (V_{REF})_C &= t_{REF} - t_Z \\ (V_{IN})_C &= t_X - t_Z \end{aligned}$$

$$\frac{(V_{IN})_C}{(V_{REF})_C} = \frac{t_X - t_Z}{t_{REF} - t_Z}$$



The conversion error can then be minimized by using the above results in the expression below to calculate the corrected analog input voltage.

$$(V_{IN})_C = (V_{REF})_C \times \frac{t_X - t_Z}{t_{REF} - t_Z}$$

Where: V_{IN} = Analog input voltage to be measured

V_{REF} = Reference voltage

V_{BE1} = Shift voltage in sample/ramp amplifier

V_{BE2} = Threshold voltage of comparator

V_{CH} = C_H voltage

The GND and V_{REF} conversion sequence is arbitrary, the GND and V_{REF} conversions not being needed each time a channel (I_1 to I_6) is converted.

PIN DESCRIPTION

Pin number	Name	Symbol	Function
9 to 13 15	Analog input	I_1 thru I_6	Analog inputs for the six channels. One of the 6 is selected by a specific bit pattern on A_0 to A_2 .
16 1 2	Channel selection input	A_0 A_1 A_2	Input for selecting an analog input channel. Either GND, one of channels I_1 to I_6 or V_{REF} is selected by a specific bit pattern on the 3 inputs.
3	RAMP START signal input	RAMP START	A/D conversion start signal input. RAMP START (1 → 0) Ramp time start signal input. RAMP START (0 → 1)
7	RAMP STOP signal output	RAMP STOP	Indicates that C_H is charged over comparator reference voltage V_{BE2} . RAMP STOP (0 → 1) A/D conversion end signal (C_H discharged to comparator reference voltage). RAMP STOP (0 → 1)
4	Ramp capacitor pin	C_H	Pin for externally connecting the ramp capacitor. The value of C_H in conjunction with V_{REF} and R_{REF} establishes the ramp time.
8	Reference voltage supply pin	V_{REF}	Reference voltage supply pin. This is the the reference voltage source for determining the discharge current and the analog reference voltage for full-scale factor correction. When the channel selection input is set 111, this pin is selected for channel conversion. The full-scale factor is corrected using the conversion results. The voltage at this pin must be set to (GND + 2V) to ($V_{CC} - 2V$) and 5.25 V or less.
6	Reference resistance pin	R_{REF}	Pin for external reference resistance for setting the discharge current.
			The external resistance is connected between the power source pin (V_{CC}) and the reference resistance pin (R_{REF}). The discharge current is, then, $I_R = (V_{CC} - V_{REF})/R_{REF}$.
14	Power supply	V_{CC}	Power supply pin
5	Ground	GND	Ground pin This pin is grounded. When the channel selection input is set to 000, this terminal is selected for channel conversion. The zero offset is corrected using the conversion results.

NOTES ON USE

1. Since the impedance of the ramp capacitor pin is approximately 30M Ω (high), a resistance must not be connected in paralleled with this input. A ramp capacitor with no leakage must be used.
2. At $V_{IN} = 0V$, t_R has a finite value.
3. Since RAMP STOP is an open collector output, an external pull-up resistor is required. (For example, when a 20K Ω external pull-up resistor is used.)
4. All digital inputs/output are TTL compatible.
5. The time from RAMP START input switching (0 \rightarrow 1) to RAMP STOP output switching (1 \rightarrow 0) is ramp time t_R .
6. $t_{SL} \geq t_A (\max) = \frac{C_H}{150\mu A - I_R} \times (V_{REF} + 0.7V)$

$$7. t_R \doteq \frac{C_H}{I_R} \times V_{IN}, t_R (\max) \doteq \frac{C_H}{I_R} \times V_{REF}$$

$$8. I_R = \frac{V_{CC} - V_{REF}}{R_{REF}}$$

$$9. 2V \leq V_{REF} \leq (V_{CC} - 2V) \text{ and } V_{REF} \leq 5.25V$$

10. While and analog input voltage is being sampled, channel selection signals A_0 , A_1 , and A_2 must not be changed for (t_{SL}).

11. When I_R is little, Linearity Error extends. However, Linearity Error is ± 0.2 [% of FSR] or less in $I_R (\min) = 12 \mu A$.

TYPICAL CHARACTERISTICS CURVES

Fig. 5 – LINEARITY ERROR vs INPUT VOLTAGE

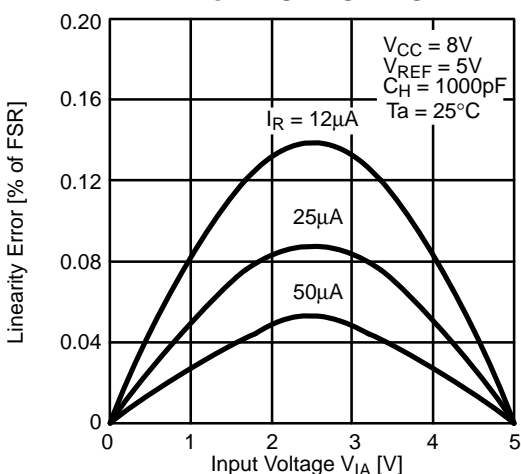


Fig. 6 – PEAK LINEARITY ERROR vs AMBIENT TEMPERATURE T_a

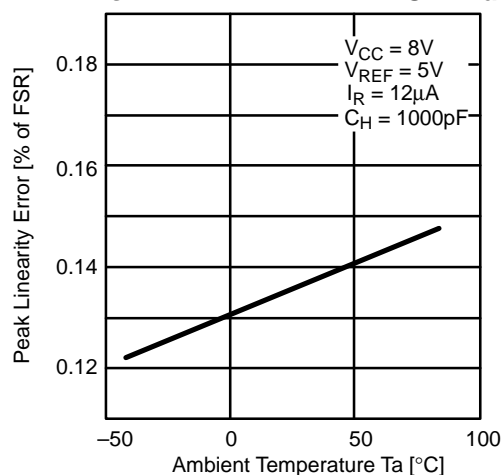
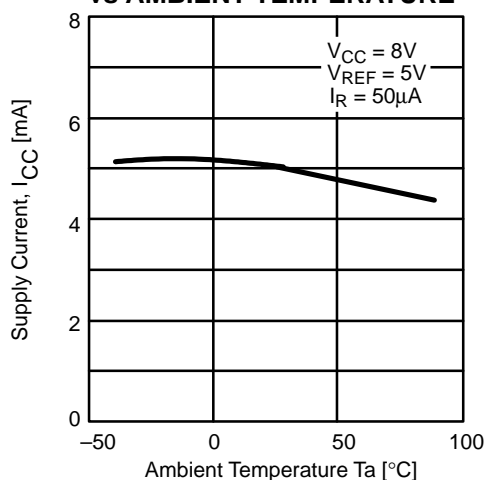


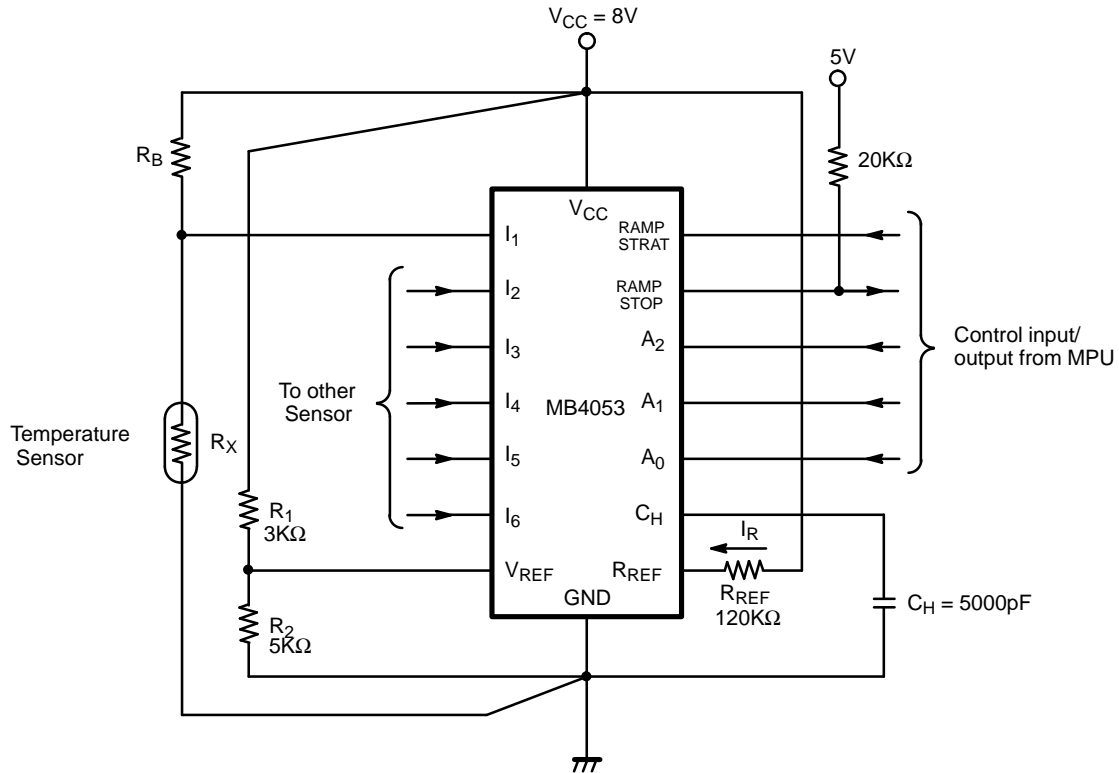
Fig. 7 – SUPPLY CURRENT vs AMBIENT TEMPERATURE



APPLICATION EXAMPLES

Examples of analog voltage (0 – 5V) A/D conversion with 10-bit resolution are shown in Fig.6 and Fig.7.

Fig. 8 – Application Example



$$\text{Reference Voltage: } V_{\text{REF}} = \frac{R_2}{R_1 + R_2} \cdot V_{\text{CC}} \quad \text{7-1}$$

$$\text{Ramp Current: } I_{\text{R}} = \frac{R_1}{R_1 + R_2} \cdot \frac{1}{R_{\text{REF}}} \cdot V_{\text{CC}} \quad \text{7-2}$$

$$\text{Input Voltage: } V_{\text{IN}} = \frac{R_X}{R_X + R_B} \cdot V_{\text{CC}} \quad \text{7-3}$$

$$\begin{aligned} \text{Ramp Time: } t_{\text{R}} &\cong V_{\text{IN}} \cdot \frac{C_{\text{H}}}{I_{\text{R}}} \\ &= \frac{R_X}{R_X + R_B} \cdot \left(1 + \frac{R_2}{R_1}\right) \cdot C_{\text{H}} \cdot R_{\text{REF}} \quad \text{7-4} \end{aligned}$$

$$V_{\text{REF}} = \frac{5\text{K}\Omega}{3\text{K}\Omega + 5\text{K}\Omega} \times 8\text{V} = 5\text{V}$$

$$I_{\text{R}} = \frac{V_{\text{CC}} - V_{\text{REF}}}{R_{\text{REF}}} = \frac{8\text{V} - 5\text{V}}{120\text{K}\Omega} = 25\mu\text{A}$$

$$t_{\text{SL}} \geq \frac{C_{\text{H}} \times V_{\text{REF}}}{I_{\text{A}(\text{min})} - I_{\text{R}}} = \frac{5000\text{pF} \times (5\text{V} + 0.7\text{V})}{150\mu\text{A} - 25\mu\text{A}} = 228\mu\text{s}$$

$$t_{\text{Rmax}} \cong \frac{C_{\text{H}} \times V_{\text{REF}}}{I_{\text{R}}} = \frac{5000\text{pF} \times 5\text{V}}{25\mu\text{A}} = 100\mu\text{s}$$

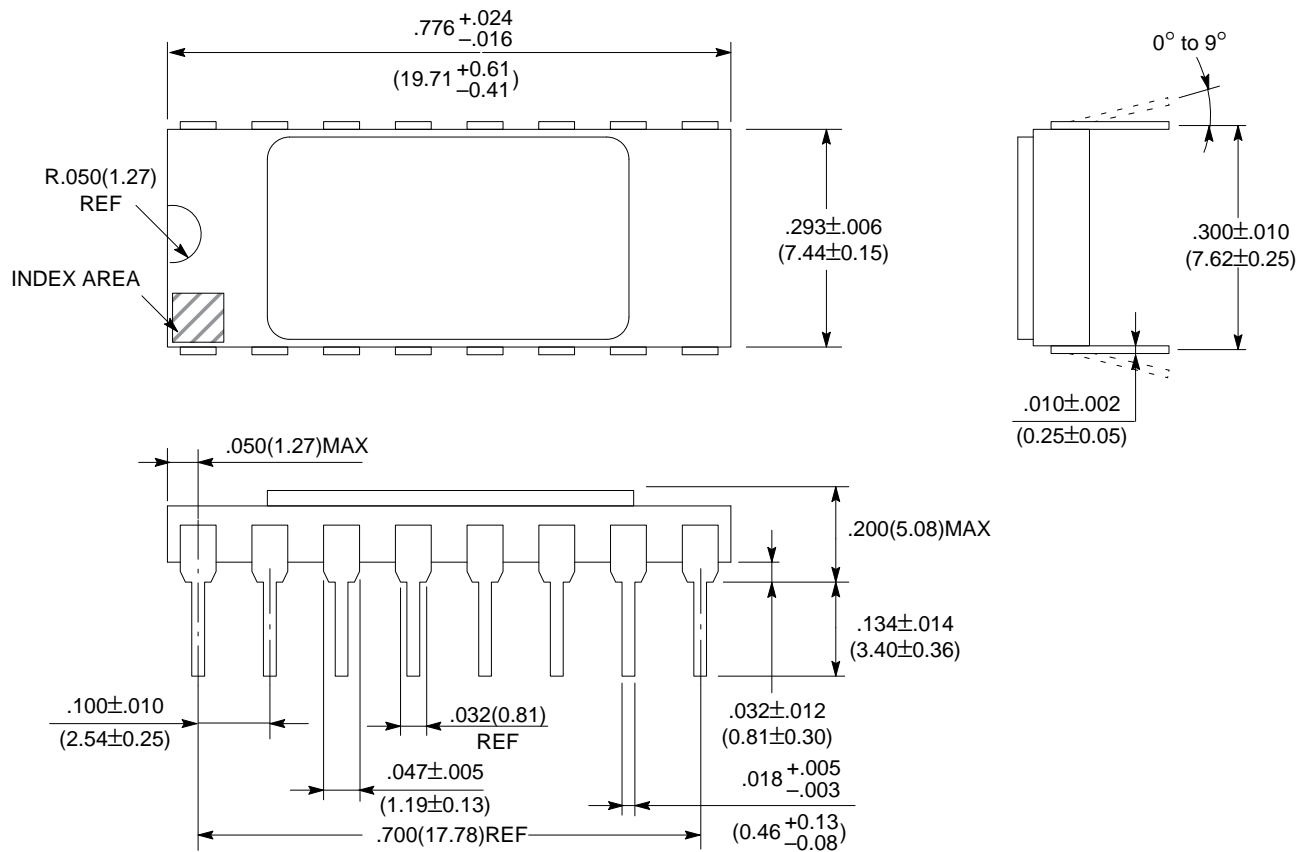
If the ramp time is counted with a 1 MHz clock, the following resolution is obtained.

$$\frac{1000\mu\text{s}}{1\mu\text{s}} = 1000 \cong 2^{10}$$

As shown in this example, the voltage output of the sensor is proportional to V_{CC} (Eq. 7-3) and V_{REF} is also proportional to V_{CC} (Eq. 7-1), the sensor output conversion results (Eq. 7-4) are not influenced by power supply voltage fluctuation. Such a conversion is called ratio metric conversion and is effective for minimizing the effects of conversion error. Supply voltage fluctuations during discharge do result in error, however.

PACKAGE DIMENSIONS

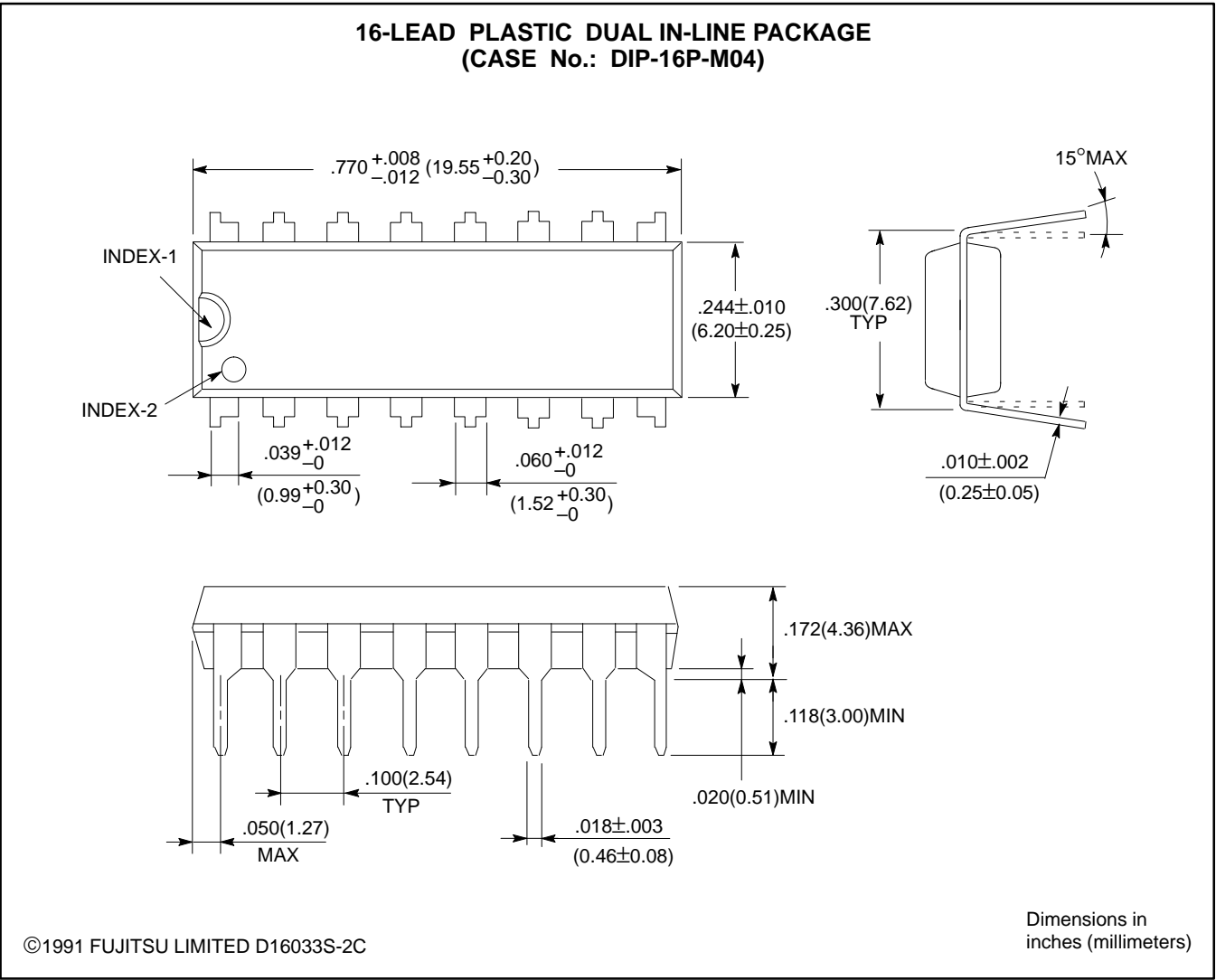
16-LEAD CERAMIC DUAL IN-LINE PACKAGE (CASE No.: DIP-16C-F02)



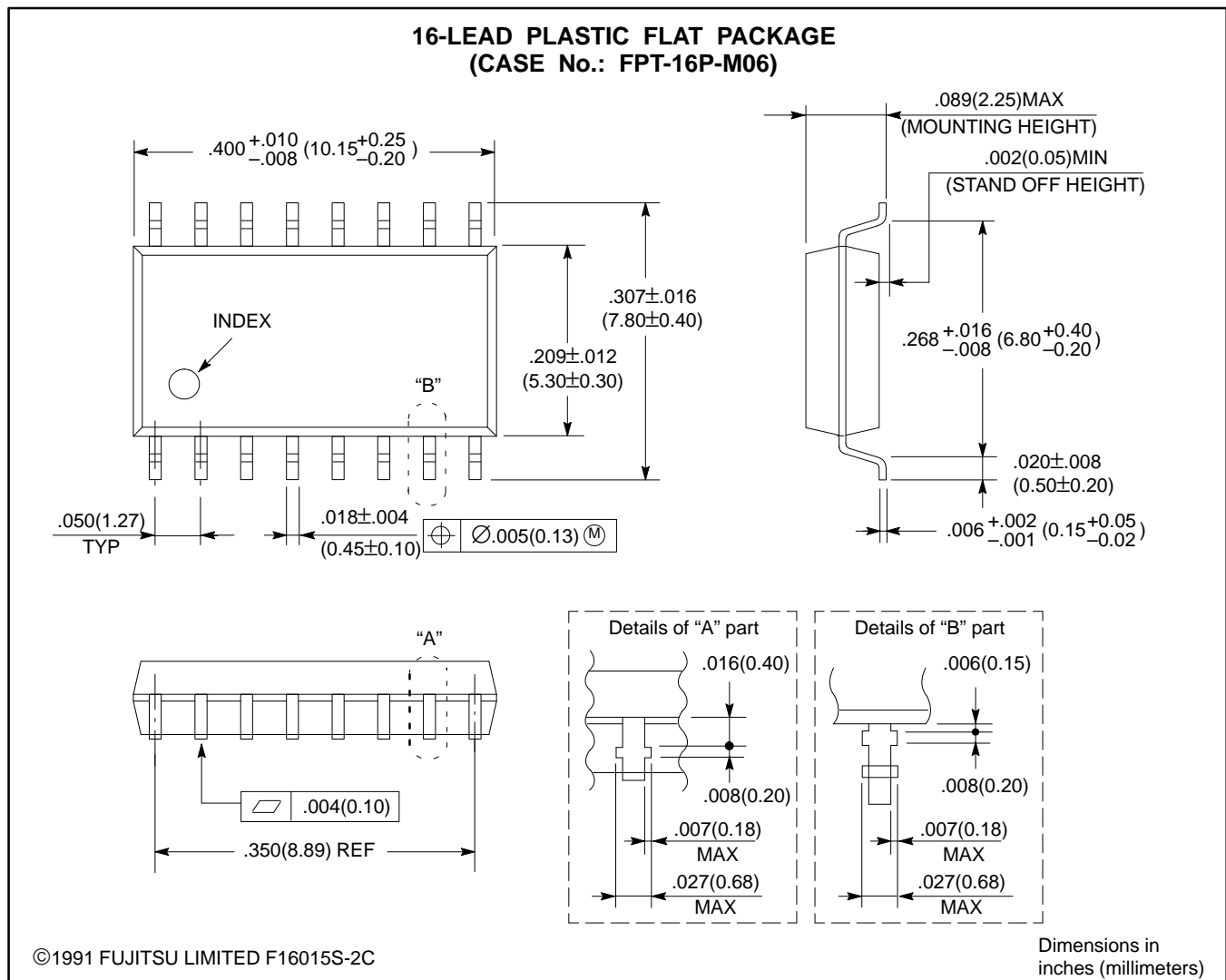
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Dimensions in
inches (millimeters)

PACKAGE DIMENSIONS (Continued)



PACKAGE DIMENSIONS (Continued)



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